

FDS5672A-NL-VB Datasheet N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)		
60	0.012 at V _{GS} = 10 V	12	10.5 nC		
00	0.015 at V _{GS} = 4.5 V	11	10.5110		



- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFET
- Optimized for "Low Side" Synchronous Rectifier Operation



APPLICATIONS

CCFL Inverter

SO-8		р С
S 1 S 2 S 3 G 4	8 D 7 D 6 D 5 D	
Top View	_	N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T	A = 25 °C, unless othe	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		12 ^a		
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	I _D	11		
Continuous Drain Current (1) = 130°C)	T _A = 25 °C	D	8.0 ^{b, c}		
	T _A = 70 °C		7.6 ^{b, c}	^	
Pulsed Drain Current	I _{DM}	25	— A		
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	4.2		
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	2.1 ^{b, c}		
Avalanche Current L = 0.1 mH Single-Pulse Avalanche Energy L = 0.1 mH		I _{AS}	15		
		E _{AS}	11.2	mJ	
	T _C = 25 °C		5		
Movimum Power Dissinction	T _C = 70 °C	P _D	3.2	w	
Maximum Power Dissipation	T _A = 25 °C	ГD	2.5 ^{b, c}	VV	
	T _A = 70 °C		1.6 ^{b, c}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	20	25	°C/VV	

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 85 °C/W.

COMPLIANT

HALOGEN

Available



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	L				<u> </u>		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 250 \mu A$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		55		~\//o(
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu\text{A}$		- 6.3		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.0		3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zana Casta Maltana Durin Connant		V _{DS} = 60 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	25			А	
		V _{GS} = 10 V, I _D = 4.6 A		0.012		0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 4.2 \text{ A}$		0.015		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 4.6 A		20		S	
Dynamic ^b				1			
Input Capacitance	C _{iss}			1100			
Output Capacitance	C _{oss}	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz		90		pF	
Reverse Transfer Capacitance	C _{rss}			55			
Total Gate Charge	Q _g	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 4.6 \text{ A}$		21 32			
				10.5	16	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 4.6 \text{ A}$		3.5			
Gate-Drain Charge	Q _{gd}			4.2			
Gate Resistance	R _g	f = 1 MHz		3.3	5	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	tr	V_{DD} = 30 V, R _L = 5.4 Ω		150	225		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 5.6 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		20	30		
Fall Time	t _f	, , , , , , , , , , , , , , , , , , ,		60	90		
Turn-On Delay Time	t _{d(on)}			10	15	ns	
Rise Time	tr	V_{DD} = 30 V, R_L = 5.4 Ω		15	25		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 5.6 \text{ A}, \text{ V}_{\text{GEN}}$ = 10 V, R_q = 1 Ω		25	40		
Fall Time	t _f	Ŭ		10	15		
Drain-Source Body Diode Characterist	ics			1			
Continous Source-Drain Diode Current	۱ _s	T _C = 25 °C			4.2		
Pulse Diode Forward Current ^a	I _{SM}				25	A	
Body Diode Voltage	V _{SD}	I _S = 2 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	, , , , , , , , , , , , , , , , , , ,		25	50	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			25	50	nC	
Reverse Recovery Fall Time	t _a	I _F = 5.5 A, dl/dt = 100 A/μs, T _J = 25 °C		19			
Reverse Recovery Rise Time	t _b			6		ns	

Notes:

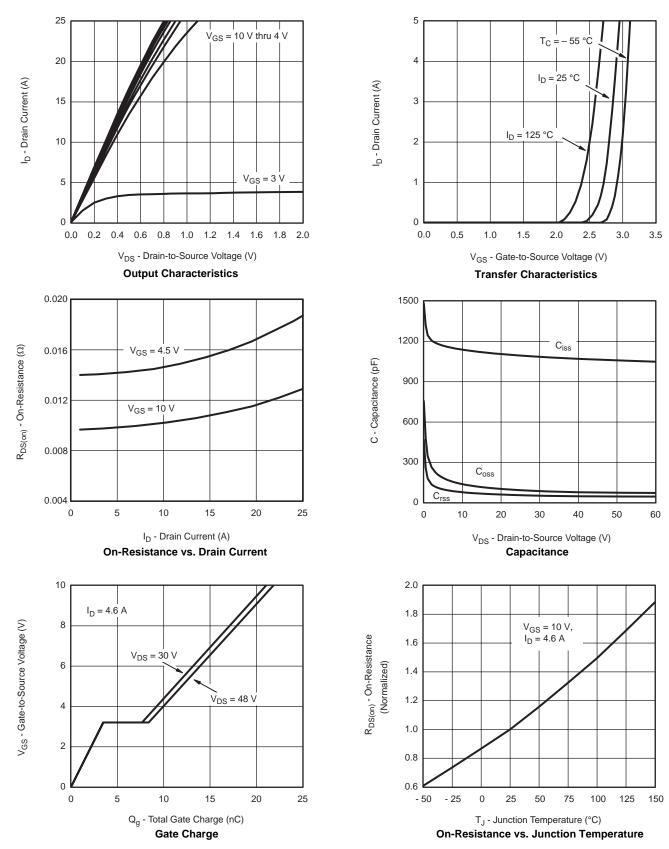
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

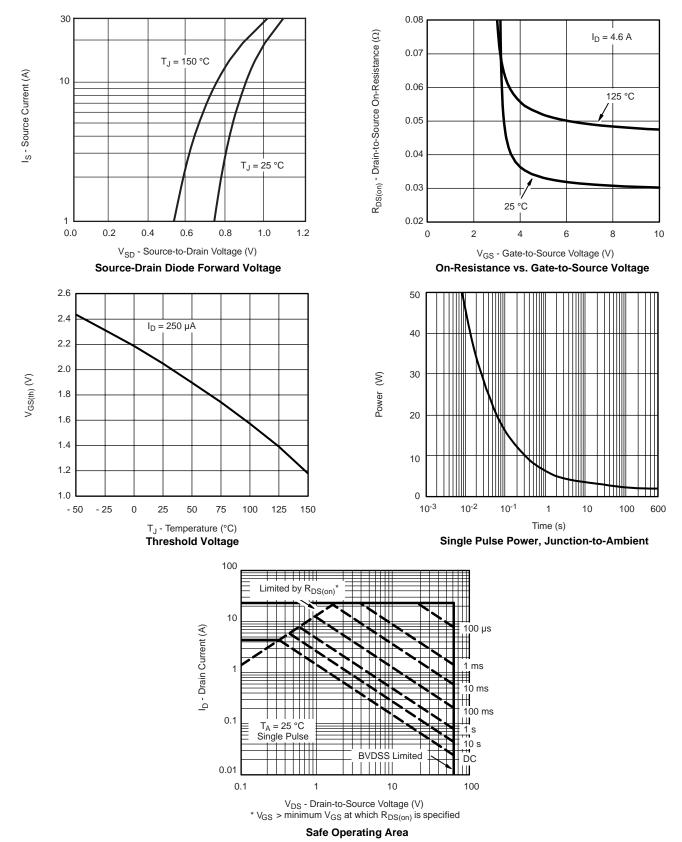






服务热线:400-655-8788

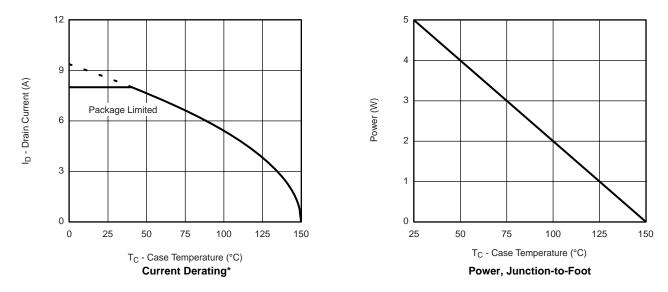




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



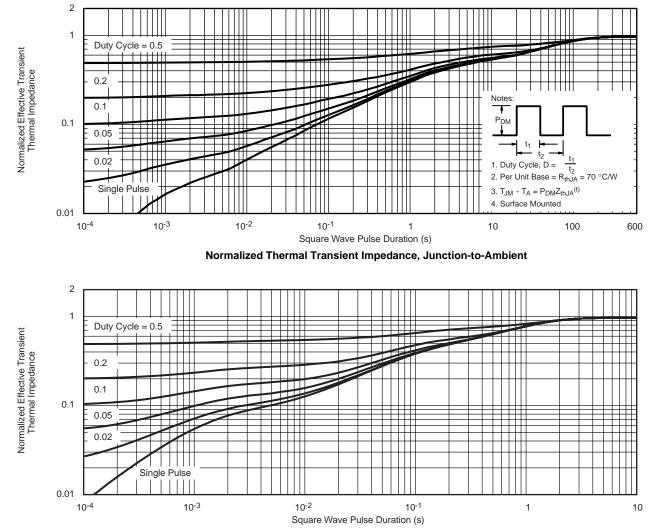
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.







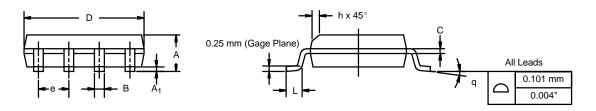
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012





	MILLIMETERS		INC	HES	
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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